/ Revised record

	! " #	$! % & '	! ( ) % * +	, -	. /
A	2016-5				
B	2019-4-20		0 1 2 3 4) 5 6 7 8 9 :	; < =	> ? @
C	2021-4-20	1	A B C D E F G 3 4 H I F G J K L M	N O P	> ? @
D	2021-10-16	4	Q R S T U V :	W X	> ? @

MMDT5551

Rev.D Oct.-2021

DATA SHEET

/ Descriptions

SOT-363 Y Z Z 2 [NPN \ ] ^ _ ` a M

Double silicon NPN transistor in a SOT-363 Plastic Package.

/ Features

b c d e f , g h MMDT5401 i j M F G k l M

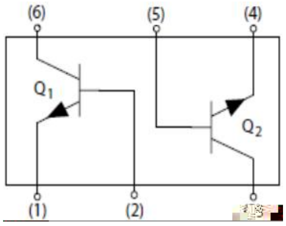
High voltage, complementary pair with MMDT5401. HF Product.

/ Applications

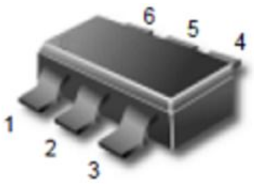
m n o p f e q r M

General purpose high voltage amplifier.

/ Equivalent Circuit



/ Pinning



PIN1 s 4 t Emitter PIN 2 s 5 t Base PIN 3 s 6 t Collector

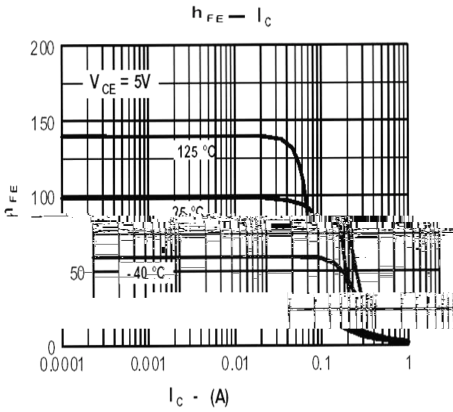
/ h_{FE} Classifications & Marking

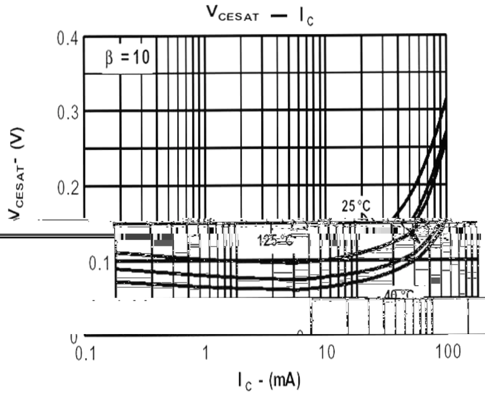
See Marking Instructions.

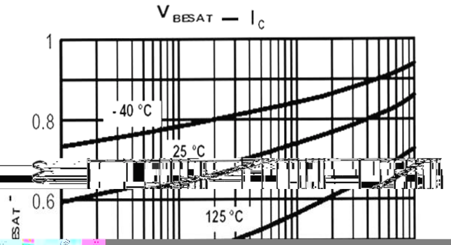
u v Parameter	w x Symbol	v y Rating
ec ge	V_{CBO}	180
ec	V_{CEO}	

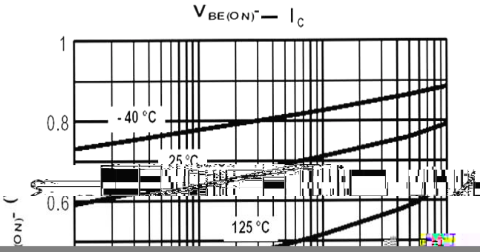
ge

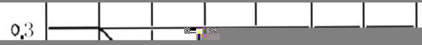
/ Electrical Characteristic Curve





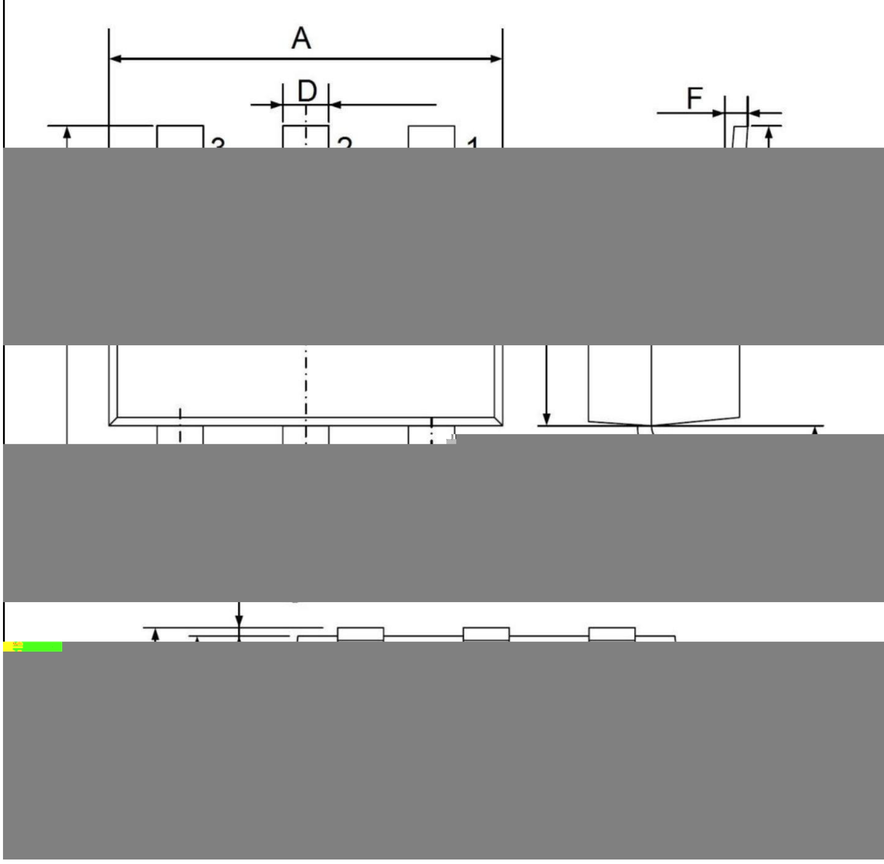






/ Package Dimensions

SOT-363-6L



[redacted]

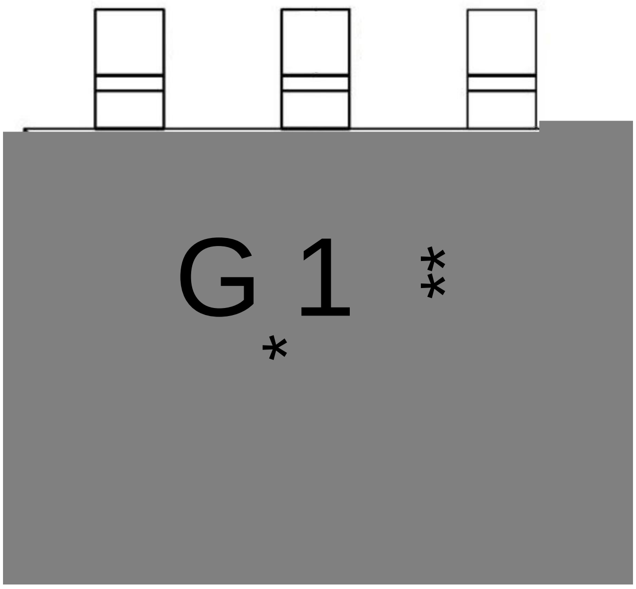
[redacted]

[redacted]

UNIT: mm

E	1.95	2.25
F	0.20 Typ.	
L	0.525 Ref.	

/ Marking Instructions



t

● t “ 1 ”

G1 t x '

***: k x ' H k x

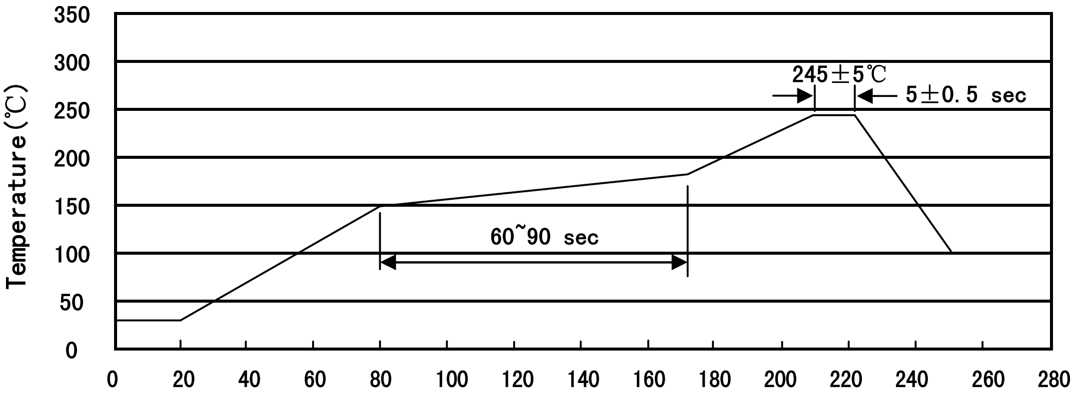
Note:

● t “1” Pin

G1 t Product Type Code

***: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



	Note:
1 150 180 60 90sec;	1.Preheating:150~180℃, Time:60~90sec.
2 245±5 5±0.5sec;	2.Peak Temp.:245±5℃, Duration:5±0.5sec.
3 2 10℃/sec.	3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

260±5℃	10±1 sec.	Temp.:260±5℃	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-363	3,000	10	30,000	6	180,000	7″ ×8	180×120×180	390×385×205

/ Notices